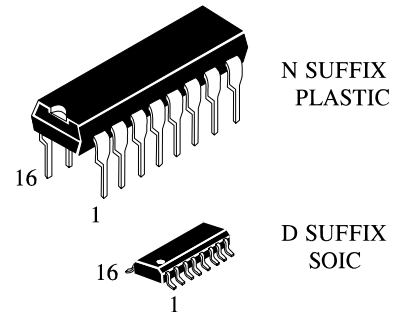


Microcircuit DS3486 consists of four differential line receivers and is a microcircuit that meets international standards of data transmission RS-422, RS-423, and it is widely used in data transmission nets, particularly in a unit for local loop of ATS.

Functions implemented

This device carries out comparing inputs with low differential signal of 200mV and gives on output full signal with load carrying capacity of $\pm 6\text{mA}$, and also has hysteresis to improve noise margin.



**Designation
Of microcircuit in package**
 DS3486N Plastic DIP
 DS3486M SOP

Truth table

Enable	input	output
L	X	Z
H	$V_{ID} \geq V_{TH}(\text{max})$	H
H	$V_{ID} \leq V_{TH}(\text{max})$	L
H	Open*	H

V_{ID} – difference of inputs A2-A1, or B2-B1, or C2-C1, or D2-D1.

V_{TH} – minimum differential input voltage.

Open* – no signals delivered to inputs.

ORDERING INFORMATION

DEVICE	Package Type	MARKING	Packing	Packing Qty
DS3486N	DIP16L	DS3486	TUBE	1000pcs/box
DS3486M/TR	SOP16L	DS3486	REEL	2500pcs/reel

Purpose of pins

# of pin	Symbol	Purpose
01	A1	Input of receiver A
02	A2	Input of receiver A
03	A	Output of receiver A
04	En A/C	input of switching outputs of A and C receivers into the third state
05	C	Output of receiver C
06	C2	2 Input of receiver C
07	C1	1 Input of receiver C
08	GND	General pin
09	D1	1 Input of receiver D.
10	D2	2 Input of receiver D.
11	D	Output of receiver D.
12	En B/D	input of switching outputs of B and D receivers into the third state
13	B	Output of receiver B.
14	B2	2 Input of receiver C
15	B1	1 Input of receiver C
16	V _{CC}	Pin of power supply from source of voltage

L – Low voltage level
 H – High voltage level
 X – any level of voltage
 Z – the third state of output .

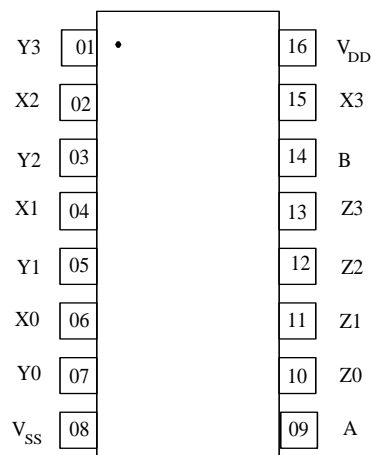

Figure 2 Designation of pins in package

Figure 3. Block diagram of microcircuit.

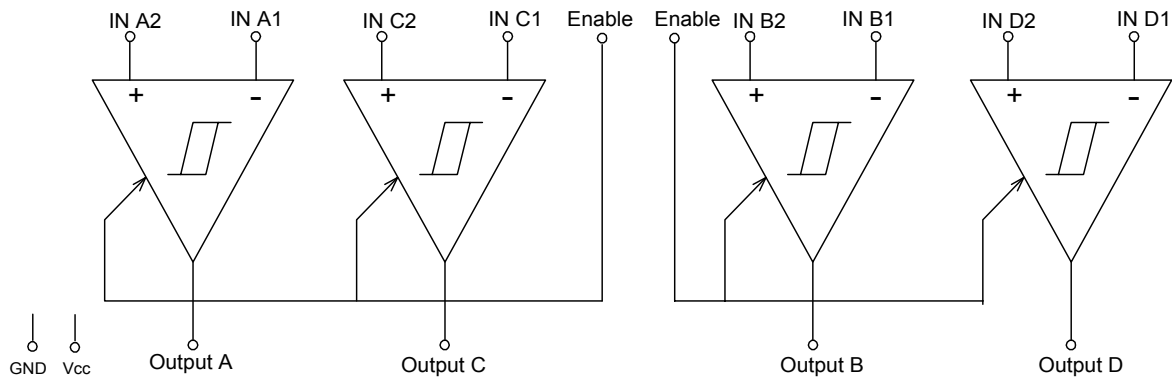


Table 1 – Limiting and extreme parameters

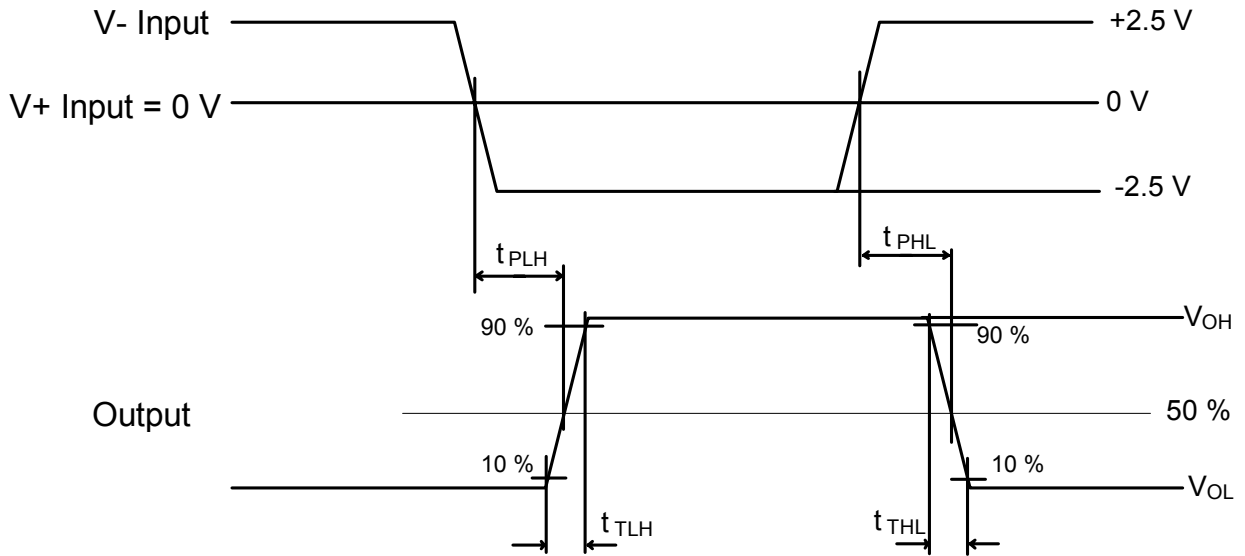
Parameter	Symbol	Limiting mode		Extreme mode		Units of measurement
		min	max	min	max	
Supply voltage	V_{CC}	4.50	5.50	—	7	V
Input voltage	V_{CM}	—	—	-14	14	
differential input voltage	V_{DIFF}	—	—	-14	14	
Voltage on input Enable	V_{IN}	—	—	—	7	
Output current	—	—	—	-25	+25	mA
transition time when switching in, switching off on input Enable	t_r, t_f	—	500	—	—	nñ
Dissipated power	DIP	P_D	—	—	1645	mW
	SO		—	—	1190	
Operation temperature	T_A	-40	+85	—	—	°Ñ
Storage temperature	T_{STG}	—	—	-65	+150	
Temperature of soldering, 4ñ	T_L	—	—	—	260	

* - at increasing temperature higher than 25°Ñ P_D decreased on 13.89mW/°C for DIP package and on 9.80mW/°C for SO package.

Table 2 -Electric parameters
 $T = -40^{\circ} \div +85^{\circ}C$

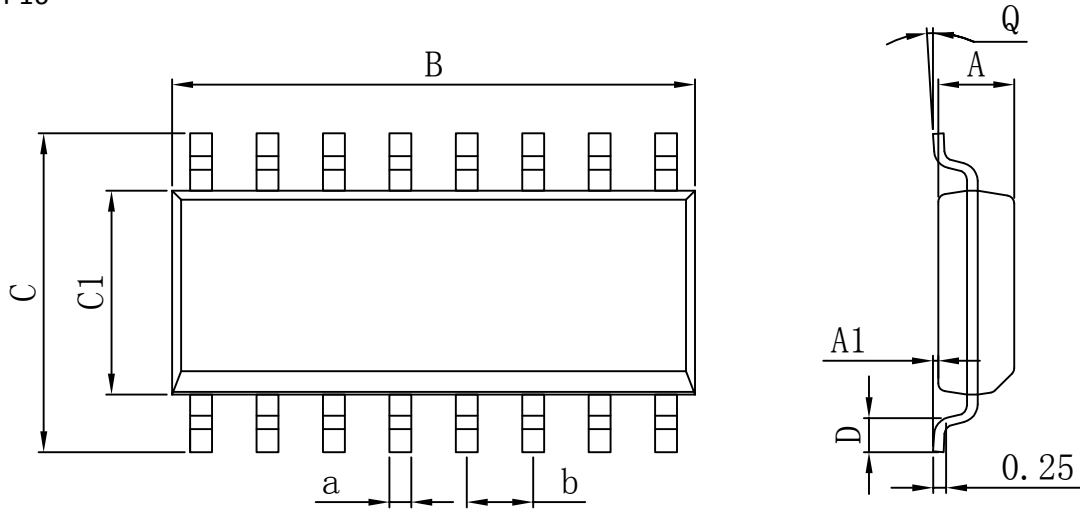
Parameter	Symbol	Conditions of measurement	standard		Units of measurement
			min	max.	
Minimum differential input voltage	V_{TH}	$-7V < V_{Cm} < +7V$	-200	200	mV
input resistance	R_{IN}	$V_{IN} = -7V, +7V$ (the rest inputs on "ground")	5.0	10	k Ω m
input current	I_{IN}	$V_{IN} = -10V$ (the rest inputs on "ground")	—	+1.5	mA
		$V_{IN} = +10V$ (the rest inputs on "ground")	—	-2.5	
minimum output voltage of high level	V_{OH}	$V_{CC} = 4.5V, V_{DIFF} = +1V, I_{OUT} = -6.0mA$	3.8	—	V
maximum output voltage of low level	V_{OL}	$V_{CC} = 5.5V, V_{DIFF} = -1V, I_{OUT} = +6.0mA$	—	0.3	
minimum input voltage of high level on input Enable	V_{IH}	—	2.0	—	V
maximum input voltage of low level on input Enable	V_{IL}	—	—	0.8	
maximum output current of the third state	I_{OZ}	$V_{OUT} = V_{CC}$ or $0V$	—	± 0.5	μA
maximum input current on input Enable	I_I	$V_{IN} = V_{CC}$ or $0V$	—	± 1.0	μA
consumption current	I_{CC}	$V_{CC} = 5.5V, V_{DIFF} = +1V$	—	23	mA
time of propagation delay at switching off, switching on	t_{PLH}, t_{PHL}	$C_L = 50pF, V_{DIFF} = 2.5V, V_{Cm} = 0V$	—	30	ns
Transition time when switching in, switching off	t_{RISE}, t_{FALL}	$C_L = 50pF, V_{DIFF} = 2.5V, V_{Cm} = 0V$	—	9	
time of the third state propagation delay on input Enable	t_{PLZ}, t_{PHZ}	$C_L = 50pF, V_{DIFF} = 2.5V, R_L = 1000k\Omega$	—	18	
time of the third state propagation delay on input Enable	t_{PZL}, t_{PZH}	$C_L = 50pF, V_{DIFF} = 2.5V, R_L = 1000k\Omega$	—	21	

Figure 4 – Time diagram of signals at changing dynamic parameters t_{PLH} , t_{PHL} , t_{TLH} , t_{THL} , t_{PZH} , t_{PHZ} , t_{PZL} , t_{PLZ}



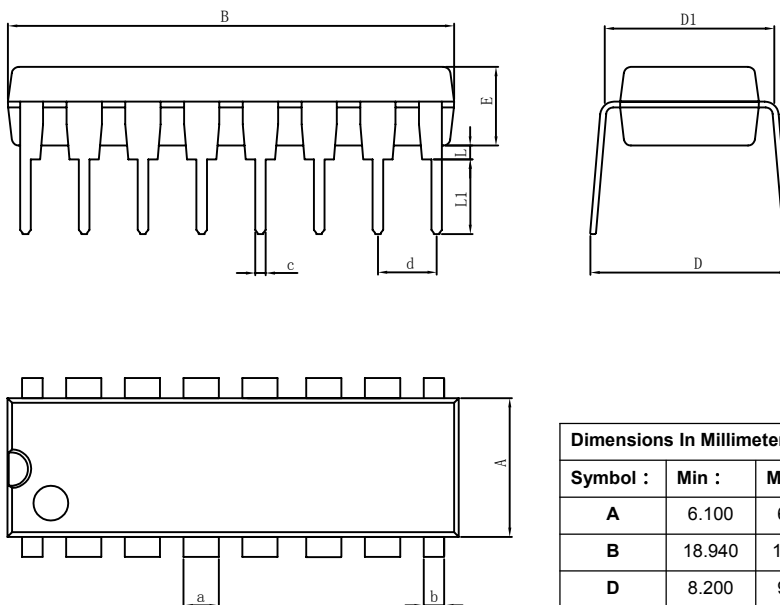
PACKAGE

SOP16



Dimensions In Millimeters					
Symbol :	Min :	Max :	Symbol :	Min :	Max :
A	1.225	1.570	D	0.400	0.950
A1	0.100	0.250	Q	0°	8°
B	9.800	10.00	a	0.420 TYP	
C	5.800	6.250	b	1.270 TYP	
C1	3.800	4.000			

DIP16



Dimensions In Millimeters					
Symbol :	Min :	Max :	Symbol :	Min :	Max :
A	6.100	6.680	L	0.500	0.800
B	18.940	19.560	a	1.524 TYP	
D	8.200	9.200	b	0.889 TYP	
D1	7.42	7.820	c	0.457 TYP	
E	3.100	3.550	d	2.540 TYP	
L	0.500	0.800			

Important statement:

Huaguan Semiconductor Co,Ltd. reserves the right to change the products and services provided without notice. Customers should obtain the latest relevant information before ordering, and verify the timeliness and accuracy of this information.

Customers are responsible for complying with safety standards and taking safety measures when using our products for system design and machine manufacturing to avoid potential risks that may result in personal injury or property damage.

Our products are not licensed for applications in life support, military, aerospace, etc., so we do not bear the consequences of the application of these products in these fields.

Our documentation is only permitted to be copied without any tampering with the content, so we do not accept any responsibility or liability for the altered documents.

单击下面可查看定价，库存，交付和生命周期等信息

[>>HGSEMI\(华冠\)](#)